

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
700V	850mΩ@10V	6.5A

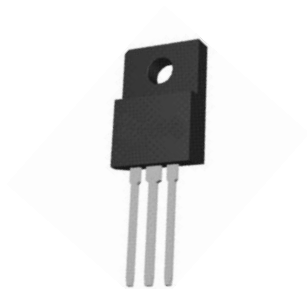
Feature

- Low on-resistance
- Low gate charge

Application

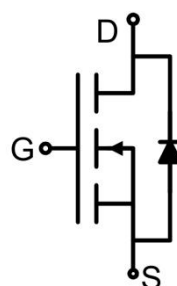
- Power factor correction (PFC)
- Uninterruptible power supply (UPS)

Package

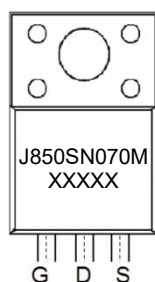


ITO-220AB

Circuit diagram



Marking



Absolute maximum ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	700	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current	I _D	6.5	A
Pulsed Drain Current ¹⁾	I _{DM}	12	A
Single Pulse Avalanche Energy ²⁾	E _{AS}	125	mJ
Power Dissipation ³⁾	P _D	25.5	W
Thermal Resistance, Junction-to-Case	R _{θJC}	4.9	°C/W
Operating Junction Temperature	T _J	-55 ~ +150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	700			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =650V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±30V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.8	3.3	3.8	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =2.5A		750	850	mΩ
Dynamic characteristics ⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, f =1MHz		339		pF
Output Capacitance	C _{oss}			25		
Reverse Transfer Capacitance	C _{rss}			1.36		
Total Gate Charge	Q _g	V _{DS} =325V, V _{GS} =10V, I _D =5A		8.1		nC
Gate-Source Charge	Q _{gs}			1.8		
Gate-Drain Charge	Q _{gd}			3.2		
Turn-on delay time	t _{d(on)}	V _{DS} =325V, V _{GS} =10V, I _D =5A R _G =25Ω		31		nS
Turn-on rise time	t _r			15		
Turn-off delay time	t _{d(off)}			56.5		
Turn-off fall time	t _f			12.5		
Source-Drain Diode characteristics						
Source-drain current	I _S				6.5	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =5A			1.3	V
Reverse Recovery Time	T _{rr}	V _{GS} =0V, I _S =5A di/dt =100A/us		162		nS
Reverse Recovery Charge	Q _{rr}			1.093		μC
Peak Reverse Recovery Current	I _{rrm}			13.5		A

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2) The EAS data shows Max. rating . L=0.5mH, I_{AS}=2.3A, V_{DD}=50V, R_G=25Ω.
- 3) The power dissipation is limited by 150°C junction temperature.
- 4) Guaranteed by design, not subject to production testing.

Typical Characteristics

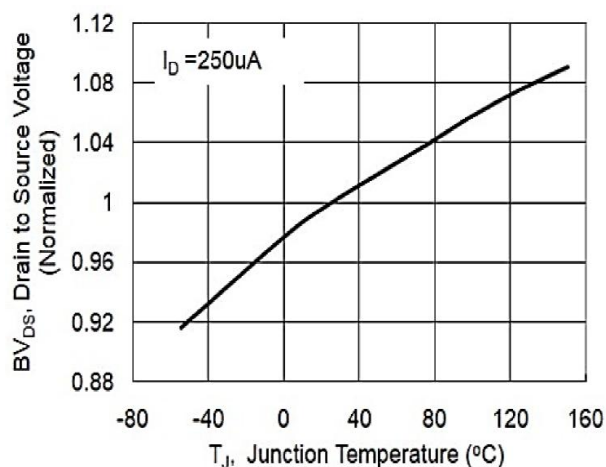


Figure 1. BV DSS vs Junction Temperature

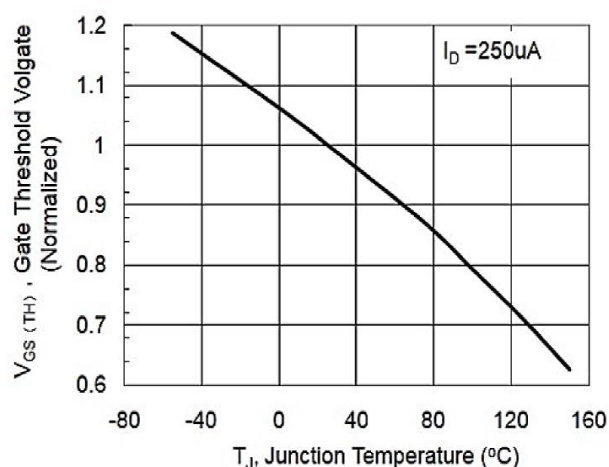


Figure 2. $V_{GS(TH)}$ vs Junction Temperature

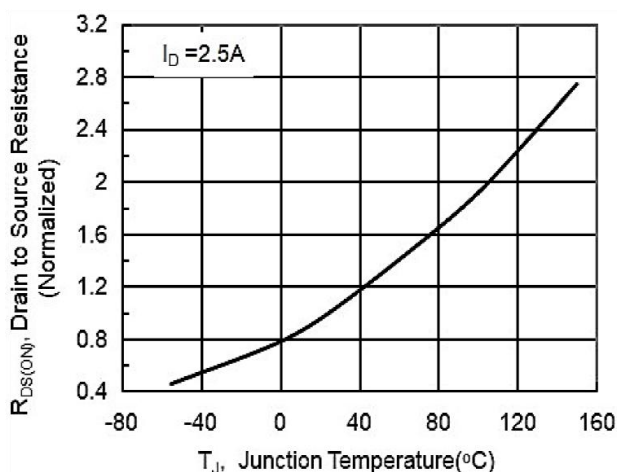


Figure 3 RDS(ON) vs Junction Temperature

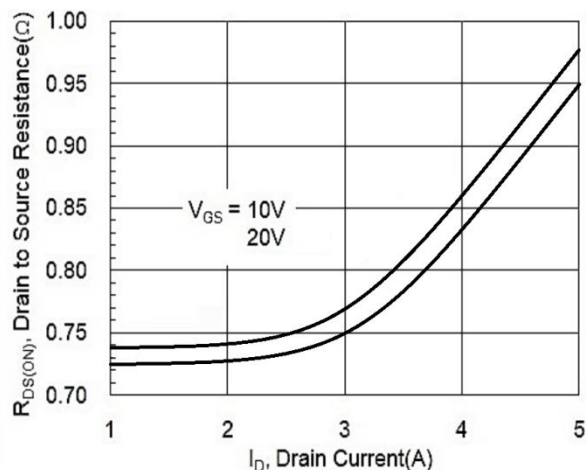


Figure 4. Drain-source on-state

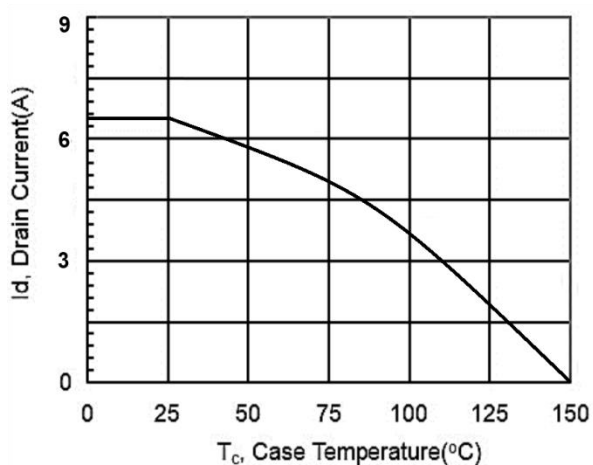


Figure 5. Drain current

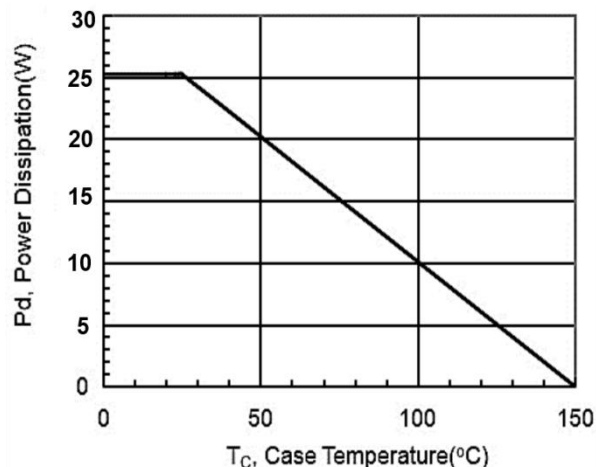


Figure 6. Power dissipation

Typical Characteristics

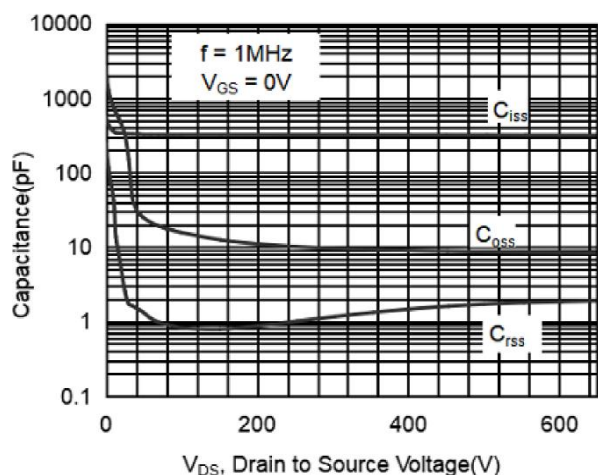


Figure7. Capacitance Characteristics

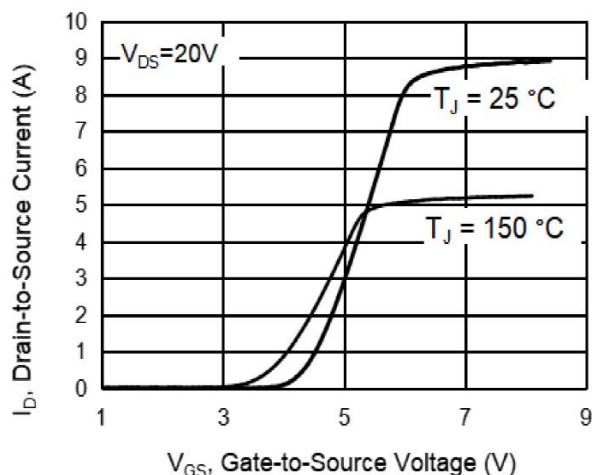


Figure8 . Transfer characteristics

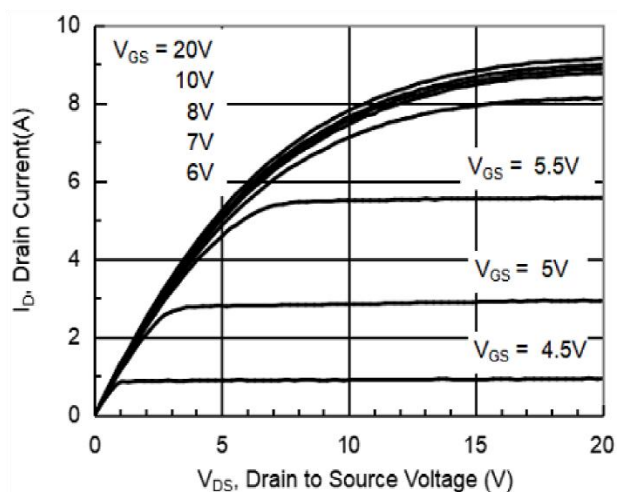


Figure 9. QOSS vs Drain-source voltage

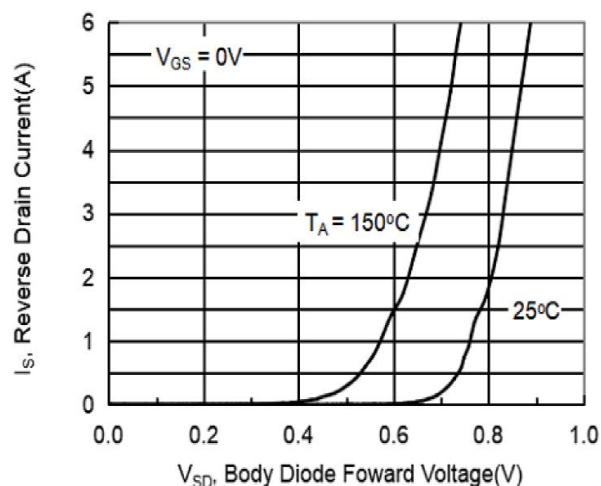


Figure 10. EOSS vs Drain-source voltage

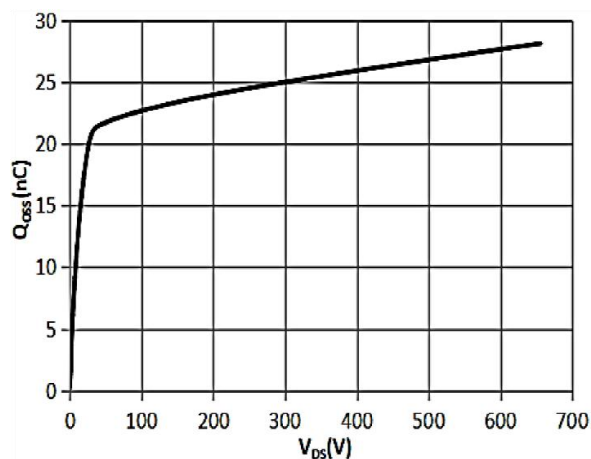


Figure 11. QOSS vs Drain-source voltage

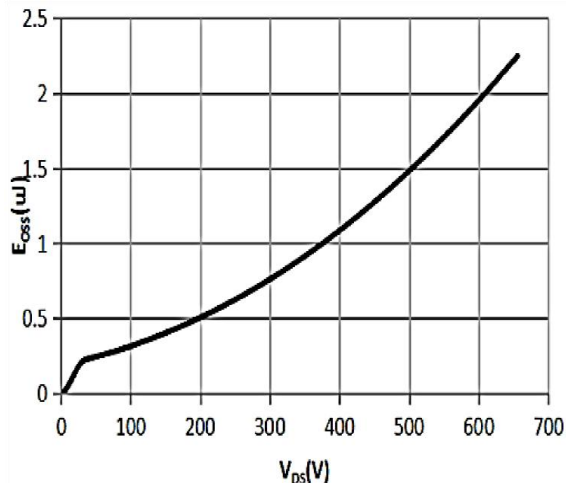


Figure 12. EOSS vs Drain-source voltage

Typical Characteristics

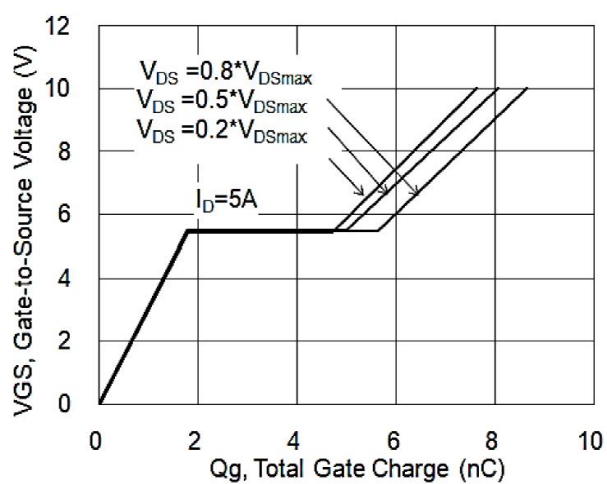
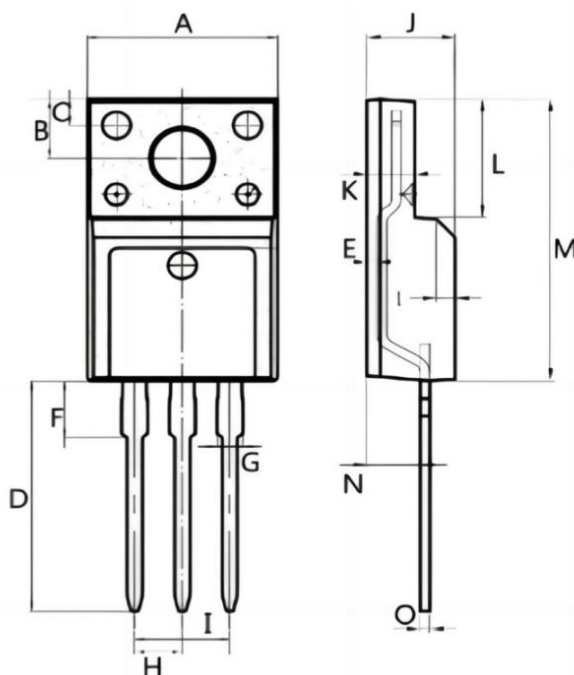


Figure 13. Gate charge characteristics

ITO-220AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.900	10.300	0.390	0.406
B	2.900	3.500	0.114	0.138
C	1.150	1.450	0.045	0.057
D	12.750	13.250	0.502	0.522
E	0.550	0.750	0.022	0.030
F	3.100	3.500	0.122	0.138
G	1.250	1.450	0.049	0.057
H	2.540 BSC.		0.100 BSC.	
I	5.080 BSC.		0.200 BSC.	
J	4.550	4.750	0.179	0.187
K	2.400	2.700	0.094	0.106
L	6.350	6.750	0.250	0.266
M	15.000	16.000	0.591	0.630
N	2.750	3.150	0.108	0.124
O	0.450	0.600	0.018	0.024